

AUIRF1010ZL-VB Datasheet N-Channel 60 V (D-S) 175 °C MOSFET

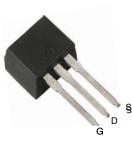
PRODUCT SUMMARY			
V _{DS} (V)	60		
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.006		
I _D (A)	120		
Configuration	Single		
Package	TO-262		

TO-262

FEATURES

- Trench power MOSFET
- Package with low thermal resistance
- AEC-Q101 qualified ^d
- 100 % R_g and UIS tested





Top View

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \degree C$, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	60	V		
Gate-Source Voltage		V _{GS}	± 20	v		
Continuous Drain Current	T _C = 25 °C ^a	1	120			
	T _C = 125 °C	l _D	80			
Continuous Source Current (Diode Conduction) ^a		۱ _S	120	А		
Pulsed Drain Current ^b		I _{DM}	480			
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	65			
Single Pulse Avalanche Energy	L = 0.1 IIIH	E _{AS}	211	mJ		
Maximum Power Dissipation ^b	T _C = 25 °C	D	230	W		
	T _C = 125 °C	P _D	76			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)		R _{thJC}	0.65	0/10	

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.

SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	·				•		•
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = 250 \ \mu A$		60	-	-	v
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$		3.0	3.5	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	250	
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	120	-	-	Α
		V _{GS} = 10 V	I _D = 30 A	-	0.0060	-	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 30 A, T _J = 125 °C	-	0.0104	-	Ω
		V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	0.0129	-	
Forward Transconductance ^b	g _{fs}	V _{DS}	= 15 V, I _D = 30 A	-	94	-	S
Dynamic ^b	•			•	•		•
Input Capacitance	C _{iss}			-	5196	6495	pF
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	-	708	885	
Reverse Transfer Capacitance	C _{rss}]		-	336	420	
Total Gate Charge ^c	Qg			-	96.5	145	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	$V_{DS} = 30 \text{ V}, I_D = 75 \text{ A}$	-	24.6	-	nC
Gate-Drain Charge ^c	Q _{gd}			-	27.2	-	
Gate Resistance	Rg		f = 1 MHz		1	1.7	Ω
Turn-On Delay Time ^c	t _{d(on)}				16	24	ns
Rise Time ^c	tr	$\begin{array}{l} V_{\text{DD}}=30~V,~R_{L}=0.4~\Omega\\ I_{\text{D}}\cong75~A,~V_{\text{GEN}}=10~V,~R_{g}=1~\Omega \end{array}$		-	14	21	
Turn-Off Delay Time ^c	t _{d(off)}			-	34	51	
Fall Time ^c	t _f			-	9	14	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed Current ^a	I _{SM}			-	-	480	Α
Forward Voltage	V _{SD}	I _F = 75 A, V _{GS} = 0		-	0.9	1.5	V

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

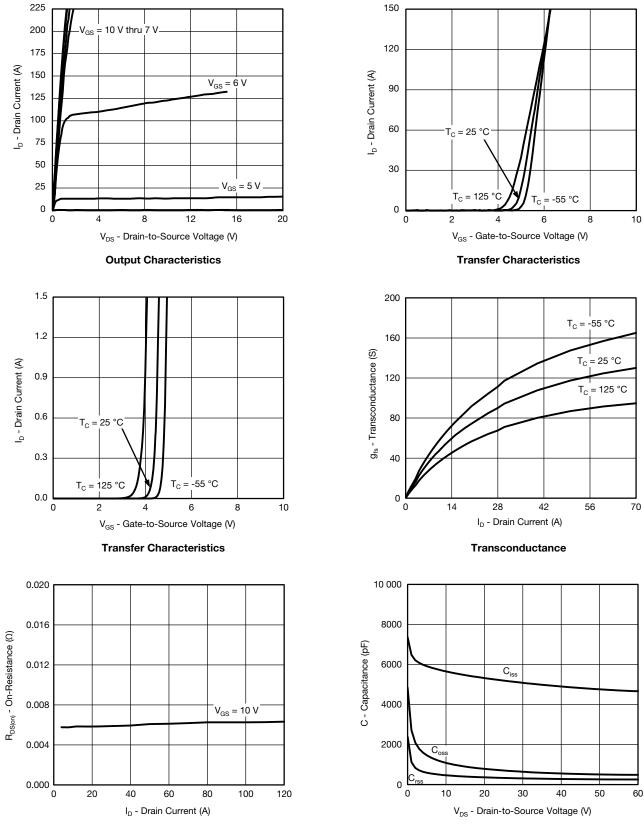
c. Independent of operating temperature.

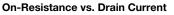
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)

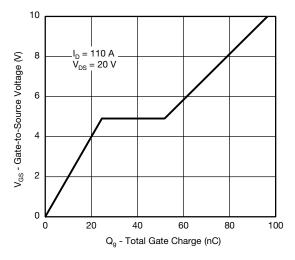




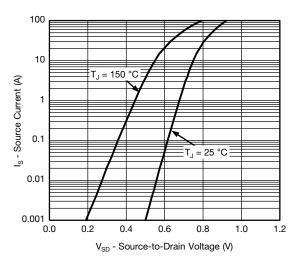




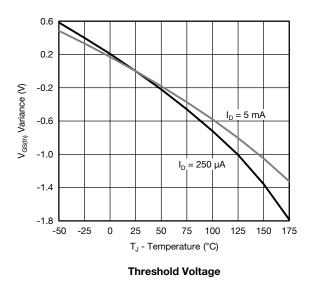
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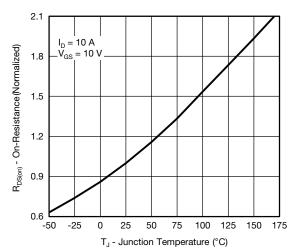


Gate Charge

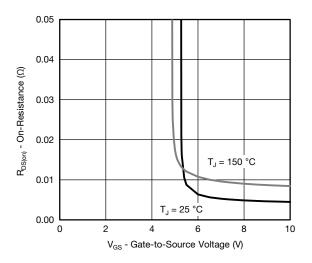


Source Drain Diode Forward Voltage

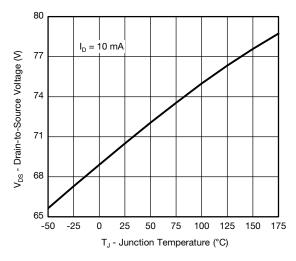




On-Resistance vs. Junction Temperature



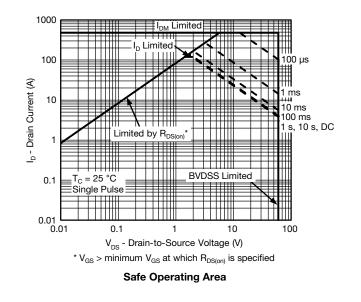
On-Resistance vs. Gate-to-Source Voltage

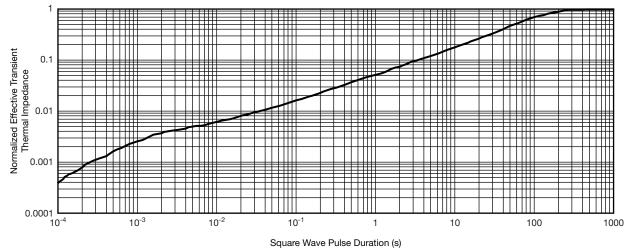


Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25 \ ^{\circ}C$, unless otherwise noted)

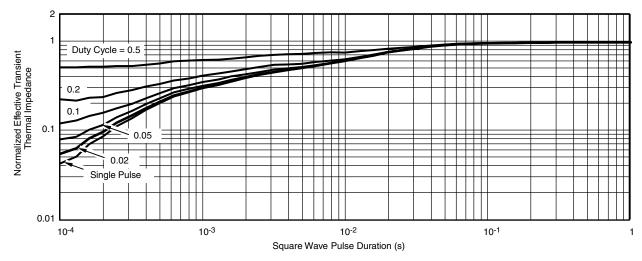




Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

• The characteristics shown in the two graphs

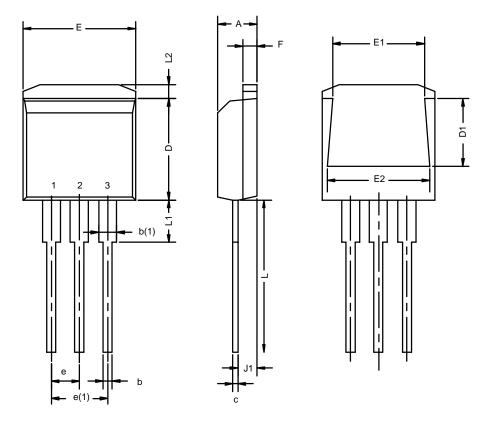
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-262: 3-LEAD



	MILLIM	ETERS*	INCHES		
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
E	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

*Use millimeters as the primary measurement



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